Draft for Public Comment

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BSI Group Headquarters

389 Chiswick High Road London W4 4AL

Tel: +44 (0)20 8996 9000
Fax: +44 (0)20 8996 7400
www.bsigroup.com

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Interested committees:

Title:	BS EN IEC 62047-51 Semiconductor Devices - Micro-electromechanical Devices Part 51: Test method of electrical characteristics under two-directional cyclic bending deformation for flexible microelectromechanical devices

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Direct tel: **020 8996 7009**
E-mail: **csc@bsigroup.com**

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Introduction

This draft standard is based on national and international discussions. Your comments on this draft are invited and will assist in the preparation of the consequent standard.

For international standards, comments will be reviewed by the relevant UK national committee before sending the consensus UK vote and comments to the international committee, which will then decide appropriate action. If the international standard is approved, it is usual for the text to be published as a British Standard.

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UK Vote

Please indicate whether you consider the UK should submit a negative (with supporting technical reasons) or positive vote on this draft. Please indicate if you are aware of any reason why this draft standard should not be published as a British Standard.

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Template for comments and secretariat observations

Date: xx/xx/20xx	Document: ISO/DIS xxxx

1	2	(3)	4	5	(6)	7
MB	Clause No./ Subclause No./Annex **(e.g. 3.1)**	Paragraph/Figure/ Table/Note	**Type of comment**	**Commend (justification for change) by the MB**	**Proposed change by the MB**	**Secretariat observations on each comment submitted**
	3.1	Definition 1	ed	Definition is ambiguous and needs clarifying.	Amend to read '...so that the mains connector to which no connection...'	
	6.4	Paragraph 2	te	The use of the UV photometer as an alternative cannot be supported as serious problems have been encountered in its use in the UK.	Delete reference to UV photometer.	

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47F/492/CD

COMMITTEE DRAFT (CD)

PROJECT NUMBER: **IEC 62047-51 ED1**	
DATE OF CIRCULATION: **2024-11-22**	CLOSING DATE FOR COMMENTS: **2025-02-14**
SUPERSEDES DOCUMENTS: **47F/447/NP, 47F/455A/RVN**	

IEC SC 47F : MICRO-ELECTROMECHANICAL SYSTEMS	
SECRETARIAT: Japan	SECRETARY: Mr Takashi Mihara
OF INTEREST TO THE FOLLOWING COMMITTEES:	HORIZONTAL FUNCTION(S):
ASPECTS CONCERNED:	

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TITLE:

Semiconductor Devices - Micro-electromechanical Devices - Part 51: Test method of electrical characteristics under two-directional cyclic bending deformation for flexible micro-electromechanical devices

NOTE FROM TC/SC OFFICERS:

This draft of CD was made based on the discussion at WG2 held on 24-05-23 in Jeju Island and the observation of 47F/455A/RVN.

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

Part XX: Test method of electrical characteristics under two-directional cyclic bending deformation for flexible micro-electromechanical devices

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International Standard IEC 62047-43 has been prepared by subcommittee 47F: Micro-electromechanical devices, of IEC technical committee 47: Semiconductor devices.

The text of this International Standard is based on the following documents:

FDIS	Report on voting
47F/XXX/FDIS	47F/XXX/RVD

Full information on the voting for its approval can be found in the report on voting indicated in the above table.

The language used for the development of this International Standard is English.

This document was drafted in accordance with ISO/IEC Directives, Part 2, and developed in accordance with ISO/IEC Directives, Part 1 and ISO/IEC Directives, IEC Supplement, available at www.iec.ch/members_experts/refdocs. The main document types developed by IEC are described in greater detail at http://www.iec.ch/standardsdev/publications.

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